



## Material Content Data Sheet



<b>Sales Product Name</b>		IPA105N15N3 G		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000771436						
<b>Package</b>		PG-TO220-3-111		<b>Weight*</b>		2241.11 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.752	0.48	0.48	4798	4798
leadframe	non noble metal	iron	7439-89-6	1.120	0.05		500	
	inorganic material	phosphorus	7723-14-0	0.336	0.02		150	
	non noble metal	copper	7440-50-8	1118.332	49.91	49.98	499008	499658
wire	non noble metal	aluminium	7429-90-5	12.792	0.57	0.57	5708	5708
encapsulation	organic material	carbon black	1333-86-4	2.171	0.10		969	
	plastics	epoxy resin	-	204.030	9.10		91040	
	inorganic material	silicondioxide	60676-86-0	879.065	39.22	48.42	392246	484255
leadfinish	non noble metal	tin	7440-31-5	7.942	0.35	0.35	3544	3544
plating	non noble metal	nickel	7440-02-0	0.305	0.01		136	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	0	136
solder	non noble metal	antimony	7440-36-0	0.426	0.02		190	
	noble metal	silver	7440-22-4	1.065	0.05		475	
	non noble metal	tin	7440-31-5	2.770	0.12	0.19	1236	1901
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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